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July 2014

FDFMA2P853

Integrated P-Channel PowerTrench® MOSFET and Schottky Diode

General Description

This device is designed specifically as a single package solution for the battery charge switch in cellular handset and other ultra-portable applications. It features a MOSFET with low on-state resistance and an independently connected low forward voltage schottky diode for minimum conduction losses.

The MicroFET 2x2 package offers exceptional thermal performance for it's physlicize and is well suited to linear mode applications.

Features

MOSFET:

 \blacksquare -3.0 A, -20V. $R_{DS(ON)}$ = 120 $m\Omega$ @ V_{GS} = -4.5 V

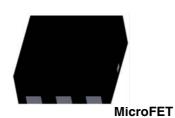
 $R_{DS(ON)} = 160 \text{ m}\Omega$ @ $V_{GS} = -2.5 \text{ V}$

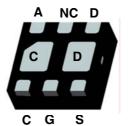
 $R_{DS(ON)} = 240 \text{ m}\Omega$ @ $V_{GS} = -1.8 \text{ V}$

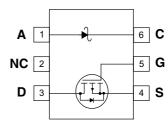
Schottky:

V_F < 0.46 V @ 500 mA

- Low Profile 0.8 mm maximun in the new package MicroFET 2x2 mm
- RoHS Compliant







Absolute Maximum Ratings T_A = 25°C unless otherwise noted

| Symbol | Parameter | Ratings | Units | |
|-----------------------------------|--|-----------|-------------|----|
| V_{DSS} | MOSFET Drain-Source Voltage | | -20 | V |
| V_{GSS} | MOSFET Gate-Source Voltage | | ±8 | V |
| | Drain Current -Continuous | (Note 1a) | -3.0 | Α |
| ID | -Pulsed | | -6 | ^ |
| V_{RRM} | Schottky Repetitive Peak Reverse voltage | | 30 | V |
| Io | Schottky Average Forward Current (Note 1a) | | 1 | Α |
| В | Power dissipation for Single Operation | (Note 1a) | 1.4 | w |
| P_{D} | Power dissipation for Single Operation | (Note 1b) | 0.7 | " |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | | -55 to +150 | °C |

Thermal Characteristics

| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 86 | |
|-----------------|---|-----------|-----|--------|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | (Note 1b) | 173 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | (Note 1c) | 86 | - C/VV |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | (Note 1d) | 140 | |

Package Marking and Ordering Information

| Device Marking | Device | Reel Size | Tape Width | Quantity |
|----------------|------------|-----------|------------|------------|
| .853 | FDFMA2P853 | 7inch | 8mm | 3000 units |

| Symbol | Parameter | Test Co | nditions | Min | Тур | Max | Units |
|--|--|--|------------------------|----------|------------|------------|-------|
| Off Char | acteristics | 1 | | | | | • |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 V$, I_D | = –250 μA | -20 | | | V |
| <u>∆BV_{DSS}</u> | Breakdown Voltage Temperature | $I_D = -250 \mu\text{A}, \text{Refe}$ | erenced to 25°C | | -12 | | mV/°C |
| ΔT _J | Coefficient | | | | -12 | <u> </u> | |
| I _{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = -16 \text{ V}, V_{G}$ | | | | -1 | μA |
| I _{GSS} | Gate-Body Leakage | $V_{GS} = \pm 8 \text{ V}, V_{D}$ | S = 0 V | | | ±100 | nA |
| On Char | acteristics (Note 2) | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D}$ | = –250 μΑ | -0.4 | -0.7 | -1.3 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate Threshold Voltage Temperature Coefficient | I _D = -250 μA, Refe | | | 2 | | mV/°C |
| $R_{DS(on)}$ | Static Drain–Source | $V_{GS} = -4.5 \text{ V}, I_{D}$ | | | 90 | 120 | mΩ |
| | On–Resistance | $V_{GS} = -2.5 \text{ V}, I_{D} = 1.8 \text{ V}, I_{D} = 1.8 \text{ V}$ | | | 120 172 | 160 240 | |
| | | $V_{GS} = -1.8 \text{ V}, I_D = -4.5 \text{ V}, I_D = -4.5 \text{ V}$ | | | 112 | 160 | |
| I _{D(on)} | On–State Drain Current | $V_{GS} = -4.5 \text{ V}, V_{D}$ | | -20 | | | Α |
| 9rs | Forward Transconductance | $V_{DS} = -5 \text{ V}, I_{D}$ | | | 7 | | S |
| | Characteristics | , 5 | | ı | ı | | |
| C _{iss} | Input Capacitance | V _{DS} = -10 V, V _O | ss = 0 V | | 435 | | pF |
| Coss | Output Capacitance | f = 1.0 MHz | | | 80 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | | 45 | | pF |
| Switchin | g Characteristics (Note 2) | • | | | | | |
| t _{d(on)} | Turn-On Delay Time | V _{DD} = -10 V, I _D | = –1 A. | | 9 | 18 | ns |
| t _r | Turn–On Rise Time | $V_{GS} = -4.5 \text{ V}, R_{GEN} = 6 \Omega$ | | | 11 | 19 | ns |
| t _{d(off)} | Turn-Off Delay Time | 1 | | | 15 | 27 | ns |
| t _f | Turn-Off Fall Time | 1 | | | 6 | 12 | ns |
| Qq | Total Gate Charge | $V_{DS} = -10 \text{ V}, I_{D} = -3.0 \text{ A}, \ V_{GS} = -4.5 \text{ V}$ | | | 4 | 6 | nC |
| Q _{gs} | Gate–Source Charge | | | | 0.8 | | nC |
| Q _{ad} | Gate-Drain Charge | | | | 0.9 | | nC |
| | ource Diode Characteristics | and Maximum | Patings | <u> </u> | Į. | <u> </u> | |
| l _s | Maximum Continuous Drain–Source | | | | | -1.1 | Α |
| V _{SD} | Drain–Source Diode Forward Voltage | V _{GS} = 0 V, I _S | = -1.1 A (Note 2) | | -0.8 | -1.2 | V |
| t _{rr} | Diode Reverse Recovery Time | $I_F = -3.0 \text{ A},$ | | | 17 | | ns |
| Q _{rr} | Diode Reverse Recovery Charge | dI _F /dt = 100 A/μs | | | 6 | | nC |
| Schottky | Diode Characteristics | | | | | | |
| I _R | Reverse Leakage | V _R = 5 V | T _J = 25°C | | 9.9 | 50 | μА |
| | | | T _J = 125°C | | 2.3 | 10 | mA |
| I _R | Reverse Leakage | V _R = 20 V | T _J = 25°C | | 9.9 | 100 | μΑ |
| | | | T _J = 85°C | | 0.3 | 1 | mA |
| | | | T _J = 125°C | | 2.3 | 10 | mA |
| V _F | Forward Voltage | I _F = 500mA | T _J = 25°C | | 0.4 | 0.46 | V |
| | | | T _J = 125°C | | 0.3 | 0.35 | |
| V _F | Forward Voltage | I _F = 1A | T _J = 25°C | | 0.5 | 0.55 | V |
| | | | T _J = 125°C | | 0.49 | 0.54 | |

Electrical Characteristics T_A = 25°C unless otherwise noted

Notes

- 1. $R_{\theta,JA}$ is determined with the device mounted on a 1 in² oz. copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta,JC}$ is guaranteed by design while $R_{\theta,JA}$ is determined by the user's board design.
 - (a) MOSFET $R_{\theta JA}$ = 86°C/W when mounted on a 1 in² pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB
 - (b) MOSFET $R_{\theta JA}$ = 173°C/W when mounted on a minimum pad of 2 oz copper
 - (c) Schottky R $_{\theta JA}$ = 86°C/W when mounted on a 1 in 2 pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB
 - (d) Schottky $R_{\theta JA} = 140^{\circ}$ C/W when mounted on a minimum pad of 2 oz copper



a) 86°C/W when mounted on a 1in² pad of 2 oz copper



b) 173°C/W when mounted on a minimum pad of 2 oz copper



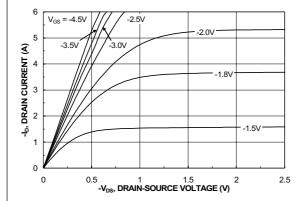
c) 86°C/W when mounted on a 1in² pad of 2 oz copper



Scale 1: 1 on letter size paper

2. Pulse Test: Pulse Width < $300\mu s$, Duty Cycle < 2.0%

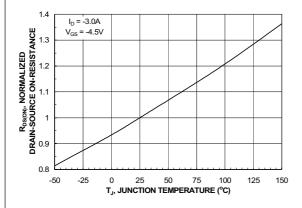
Typical Characteristics



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Figure 1. On-Region Characteristics

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage



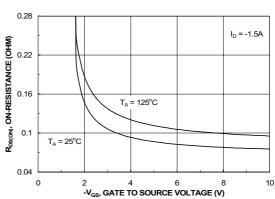
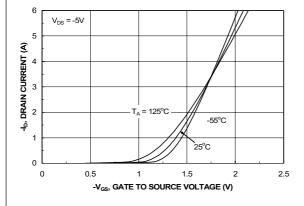


Figure 3. On-Resistance Variation with Temperature

Figure 4. On-Resistance Variation with Gate-to-Source Voltage



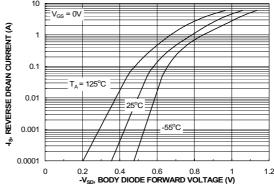
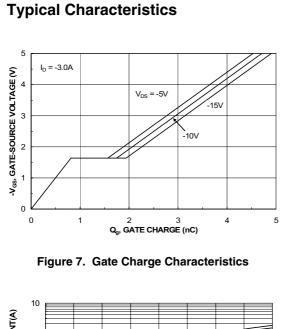


Figure 5. Transfer Characteristics

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature



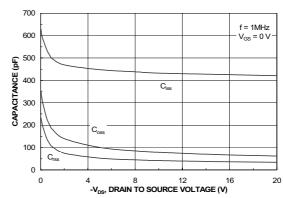
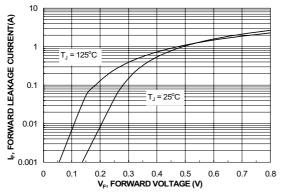


Figure 8. Capacitance Characteristics



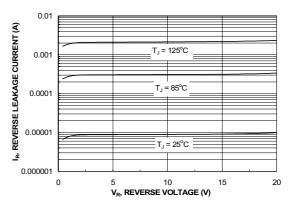


Figure 9. Schottky Diode Forward Voltage

Figure 10. Schottky Diode Reverse Current

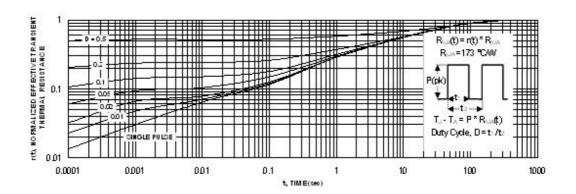
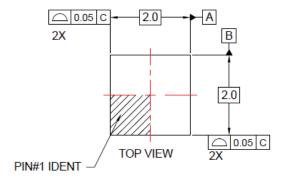
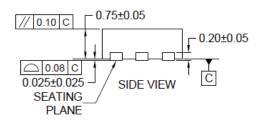


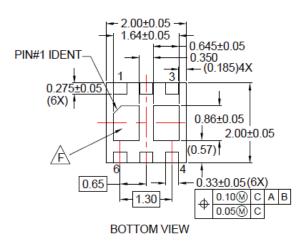
Figure 11. Transient Thermal Response Curve

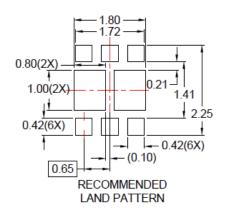
Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

Dimensional Outline and Pad Layout









NOTES:

- A. CONFORM TO JADEC REGISTRATIONS MO-229, VARIATION VCCC, EXCEPT WHERE NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-UMLP16Erev4
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